

LTM4601 118LD 15mm x 15mm x 2.82mm (TABLE OF MATERIAL DECLARATION)

The LTM4601 is RoHS compliant per EU RoHS Directive 2003/95/EC.

It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE).

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Material Analysis (weight %)
1	Substrate	Circuit Board	0.2124472				
				Barium Compounds	7727-43-7	0.00319	1.5
				Copper metal	7440-50-8	0.11897	56.0
				Copper compounds	1328-53-6	0.00004	0.018
				Ecotoxic substances	7439-92-1	0.00000	0.00043
				Gold metal or alloy	7440-57-5	0.00098	0.46
				Nickel	7440-02-0	0.00446	2.1
	Zinc	7440-66-6	0.00002	0.007			
2	Solder Paste	Alloy	0.0206249				
				Sn	7440-31-5	0.01959	95.0
				Sb	7440-36-0	0.00103	5.0
3	Passive	Customer	0.7833700	-	-	-	-
4	Wire	Gold	0.00324				
				Au	7440-57-5	0.0032397	99.99
				Others	-	0.0000003	0.01
5	Underfill	Chipcoat U8439-1	0.0069				
				Bisphenol A type liquid epoxy resin (1~5%)	25068-38-6	0.00021	3
				Bisphenol A type liquid epoxy resin (15~25%)	9003-36-5	0.00138	20
				Phenolic resin (15~25%)	9003-35-4	0.00138	20
				Silicon dioxide (50~60%)	60676-86-0	0.00380	55
				Carbon Black (<1%)	1333-86-4	0.00003	0.5
	Additive (<5%)	2530-83-8	0.00010	1.5			
6	Encapsulation	Epoxy Resin GE-100-LFC	0.90508				
				Fused Silica (60-95)	60676-86-0	0.63356	70
				Solid Epoxy resin (2-20)	-	0.09051	10.0
				Phenol resin (2-20)	-	0.09051	10.0
				Crytalline Silica (≤5)	14808-60-7	0.00905	1.0
				Carbon Black (<1)	1333-86-4	0.00453	0.5
	Metal Hyrdoxide (≤30)	-	0.08146	9.0			
Total Package weight			1.931665				

Note: Composition derived from MSDS and material C of C from Vendors;
Component Weight based on assembly of generic parts.